

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 26. (withdrawn) An overmolded die the size of a chip scale package and not having any substrate.

Claim 27. (original) A chip scale packaged die having no substrate.

Claim 28. (withdrawn) An overmolded die without a substrate, comprising:  
a die having a first surface carrying electrical contacts; and  
an encapsulated material sealing the die except for the electrical contacts.

Claim 29. (withdrawn) The overmolded die of claim 28 wherein the encapsulated material is chosen from a class consisting of epoxies, including thermo-set resins, silicons, sycar, polyimides and polyurethanes.

Claim 30. (original) An encapsulated die not having a substrate comprising:  
a die having first and second surfaces, the first surface carrying bond pads; and  
an encapsulation material sealing the second surface of the die.

Claim 31. (original) The encapsulated die of claim 30 wherein the encapsulation material seals the first surface of the die except for the bond pads.

Claim 32. (withdrawn) The encapsulated die of claim 31 wherein the encapsulation material is chosen from a class consisting of epoxies, including thermo-set resins, silicons, sycar, polyimides and polyurethanes.

Claim 33. (new) The encapsulated die of claim 31 wherein the encapsulation material is chosen from a class consisting of epoxies, including thermo-set resins.